

To: Customer

PCN # C&P-13-017

Date: July 1, 2013

TOSHIBA CORPORATION
SOCIAL INFRASTRUCTURE SYSTEMS
COMPANY

Defense & Electronic Systems Div.

Components & Parts Business Development Dept.

Page: 1 of 2

PCN(Process/Product Change Notice)
of Toshiba Microwave Semiconductor Products

Dear Madams and Sirs,

We thank you very much for your continuous patronage to our Microwave Semiconductor products. Taking this opportunity, we are glad to inform you that we are going to change the process of the production. We therefore wish to advise you for your understanding and acceptance of this change.

Sincerely yours

— NOTE —

1. Applicable Products*:

TIM1213-18L

TIM1314-9L

TIM1314-18L

TIM1414-9L

TIM1414-18L

Note*: Including custom products with above generic part numbers.

2. Description of change:

Outline of bonding pad of chip and the wiring pattern on chip to accommodate with bonding pad change.

3. Reason of change:

Production improvement of manufacturing applicable Microwave Power GaAs FET

— To be continued. —

4. Transition Dates:

The change will be implemented with deliveries after 3K1A (October 1, 2013) shipping lot.

5. Effect of Change

There is no impact to product quality and reliability. The validation data on the above improvement will be shared upon request.

6. Contact

If you have further question, please contact our local Toshiba office on this matter.

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